Special Issue

Advanced Materials and Process for 3D Printing and Flexible Electronics

Message from the Guest Editor

At the intersection between 3D printing and electronics, advanced materials are helping to bridge the gap between the creation of structure and function. Advanced materials in 3D printing include a range of advanced polymers, nanoparticles, ceramics, graphene, etc. These materials are enabling traditional and advanced electronics applications while taking advantage of the design and fabrication flexibility of additive manufacturing systems. Additive processes allow new mechanical, optical, and electronic products to be fabricated with nearly any geometry, reducing traditional manufacturing constraints.

Without doubt, ongoing developments in advanced materials will fuel future innovations in flexible electronics, additive manufacturing, 3D electronics, and beyond.

This Special Issue is focused on the latest developments and research results in novel materials for 3D printing, flexible electronics, and in the space connecting them both.

flexible electronics

additive manufacturing electronic materials photovoltaic materials

3D printing

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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